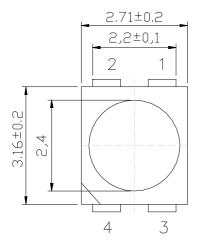
Spec	-	認 書 n For App	roval
Customer: (客)	戶)		
Description:	6品描述) 	SMD3528燈珠共	共陽RGB
Part number:	E品型號) <b>TJ-</b>	S3528UG2W9TL	_CCYRGB-A
Date: (日)	期)		
Approved By: (約 Prepared By:(我司			
Approval	Check	Design	Sales
核准		製作	業務

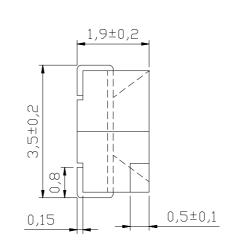
Customer Service Hotline: **400-676-8616** TEL: 0769-8662 5999 0769-8200 2226 E-MIAL:dg@togialed.com

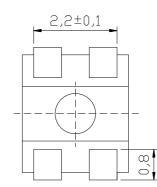
FAX: 0769-8200 2227 WEB: www.togialed.com

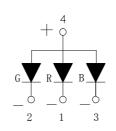


## Outline Dimension:

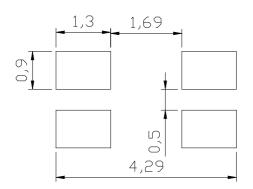








## ■ PAD Lay Out PCB





## Notes:

- 1. All dimensions are in millimeters.
- 2. Tolerance is  $\pm 0.2$  unless otherwise noted.
- 3. Specifications are subject to change without notice.

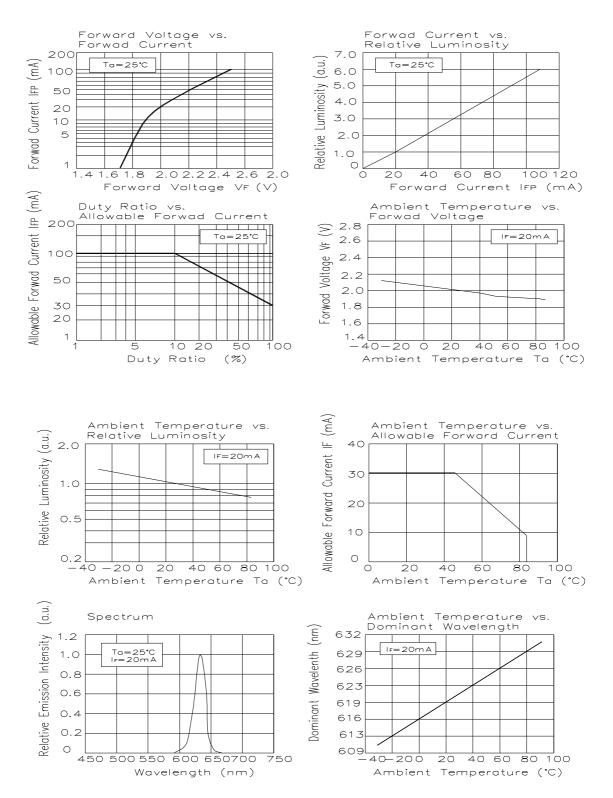
Items	Symbol	Absolute maximum Rating	Unit	
Power Dissipation	PD	200	mW	
Forward Current(DC)	IF	30	mA	
Peak Forward Current	Ifp	100	mA	
Reverse Voltage	VR	5	V	
Operation Temperature	Topr	- 40~ + 85	°C	
Storage Temperature	Tstg	- 40~ + 80	°C	
Lead Soldering Temperature	Tsol	Max.260°C for 5 sec Max. (3min from the base of the epoxy bulb)		

Pulse width≤0.1msec duty≤1/10

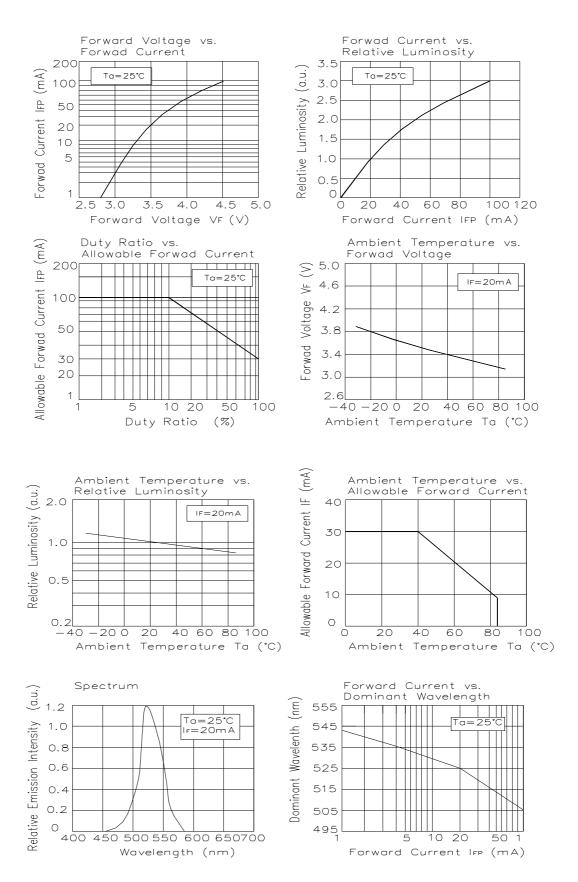
г

Typical Electrical & Optical Characteristics(Ta=25°)	

Items	Symbol	Condition	Min	Тур	Max	Unit
Forward Voltage	VF (IF=20mA)	G,B	2.8	3.0	3.4	V
		R	1.8	2.0	2.4	V
Reverse Current	IR	VR =5V			2	μA
Dominant Wavelength	$\Lambda d (I_F = 20 \text{mA})$	R	620		630	nm
		G	520		530	nm
		В	460		470	nm
Luminous Intensity	Iv ( IF =20mA)	R	300		600	mcd
		G	1200		2000	mcd
		В	300		600	mcd
View Angle	2 0 1/2	IF =20mA		120		Deg

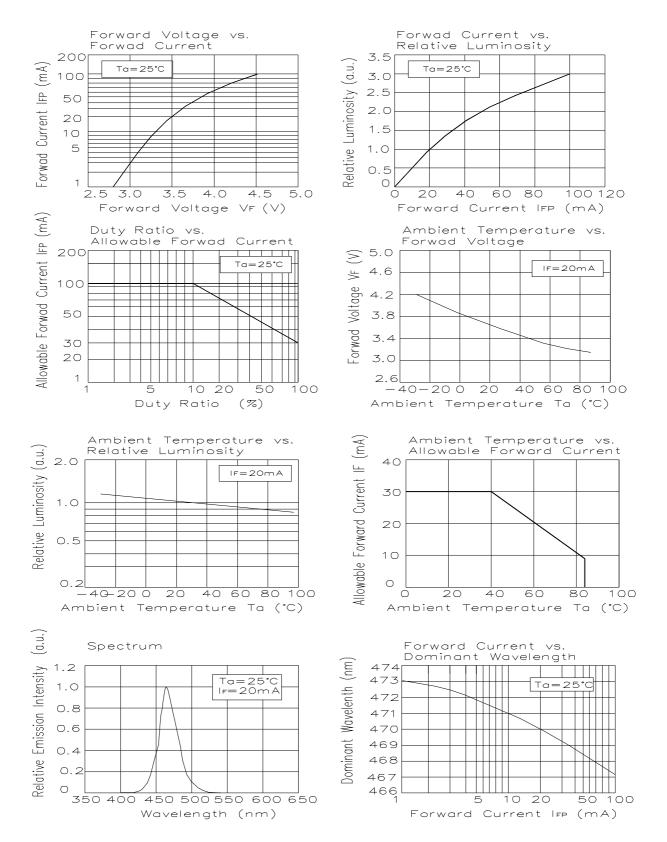


# **Typical Electrical/Optical Characteristics Curves (R):**



# **Typical Electrical/Optical Characteristics Curves (G):**

# **Typical Electrical/Optical Characteristics Curves (B):**



Classific-	T	Standard	Test	Durati-	Units	Number of
ation	Test Item	Test Method	Conditions	on	Tested	Damaged
Life Test	Operating	JIS7021:B4	$T_{\text{A}}\!\!=\!\!25^\circ\!\text{C}\pm$			
	Life Test	MIL-STD-202:107D	5℃,IF=30mA	1000h	22	0/22
		MIL-STD-750:1026				
	High	JIS7021:B10	$T_{\text{A}}$ =100 °C $\pm$			
	Temperature	MIL-STD-202:210A	5°C	1000h	22	0/22
	Storage	MIL-STD-750:2031				
	Low		$T_{A}$ = - 55 °C $\pm$			
	Temperature	JIS7021:B12	5°C	1000h	22	0/22
	Storage					
	Temp		$T_{A}$ =85 °C $\pm$			
	&Humidity	JIS7021:B11	5°C	1000h	22	0/22
<b>F</b> . (	Test	MIL-STD-202:103D	RH=85 $\% \pm$			
Environment Test			5℃RH			
Test	Shock Test	JIS7021:B4	- 10℃±5℃	50 Cycles	22	0/22
		MIL-STD-202:107D	← →100°C			
		MIL-STD-202:107D MIL-STD-750:1026	±5℃			
		MIL-STD-750:1026	5min - 5min			
			- 55℃~			
	Tommonotomo	JIS7021:A3	25°C~85	50	22	0/22
	Temperature	MIL-STD-202:107D	°C~25°C			
	Cycling Test	MIL-STD-750:1051	3min -5min-	Cycles		
			30min- 5min			
Mechanical Test	Resistance to	JIS7021:A1	$260 \pm 5^{\circ}$	1 time	22	0/22
	Soldering	MIL-STD-202:210A	260±5℃, 10±1sec			
	Heat	MIL-STD-750:2031	10±1sec			
	Lead Integrity	MIL-STD-750D	Load 2.5N	24:	22	0/22
		Method 2036.3	$0^{\circ} \sim 90^{\circ} \sim 0^{\circ}$	3time	22	0/22

### • Soldering :

1. Manual Soldering

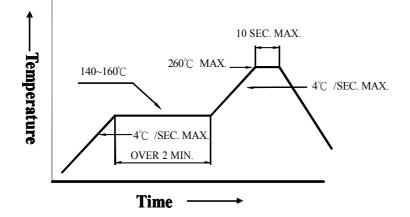
The temperature of the iron tip should not be higher than 350°C and Soldering time to be within 3 seconds per solder-pad.

2. Reflow Soldering

Preheating : 140  $^\circ C{\sim}160\,^\circ C{\pm}5\,^\circ C$  , within 2 minutes.

Operation heating : 260°C (Max.) within 10 seconds.(Max)

Gradual Cooling (Avoid quenching).

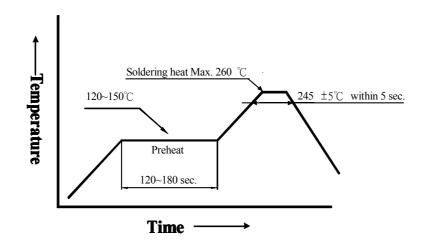


3. DIP soldering (Wave Soldering) :

Preheating : 120°C~150°C, within 120~180 sec.

Operation heating :  $245^{\circ}C \pm 5^{\circ}C$  within 5 sec.260°C (Max)

Gradual Cooling (Avoid quenching).



### • Handling :

TOG

Care must be taken not to damage LED's epoxy resin while exposing to high temperature or contact LED's epoxy resin with hard or sharp objects, such as metal hook, tweezer or sand blasting.

#### • Notes for designing:

Current limiting resistor must be used in the circuit to drive TOGIA LEDs within the rated figures and not to overload TOGIA LEDs with instantaneous voltage at the turning ON and OFF cycles.

When using pulse driving, the average current must be within the rated figures. And the circuit should be designed to avoid reverse voltage when turning off the TOGIA LEDs.

#### • Storage:

In order to avoid the absorption of moisture, it is recommended to solder TOGIA LEDs as soon as possible after unpacking the sealed envelope.

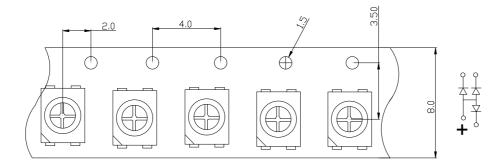
If the envelope is still packed, to store it in the environment as following:

- (1) Temperature :  $5^{\circ}$ C- $30^{\circ}$ C( $41^{\circ}$ F)Humidity : RH 60% Max.
- (2) After this bag is opened, devices that will be applied to infrared reflow, vapor-phase reflow, or equivalent soldering process must be:
  - a. Completed within 168 hours.
  - b. Stored at less than 30% RH.
- (3) Devices require baking before mounting, if:(2) a or (2) b is not met.
- (4) If baking is required, devices must be baked under below conditions:
  48 hours at 60 °C±3 °C.

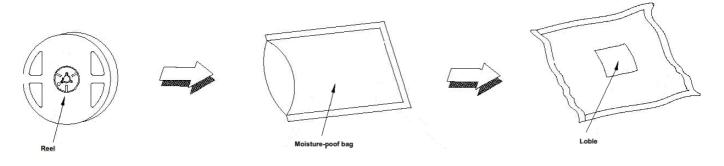
#### Package and Label of Products:

Package: Products are packed in one bag of 1000 pcs (one taping reel) and a label is attached to each bag.

## • Tapping and packaging specifications(Units: mm)



Label Aluminum moisture-proof bag Desiccant Label



#### • Package Method unit: mm)

